

Title (en)  
LED BULB

Title (de)  
LED-GLÜHLAMPE

Title (fr)  
AMPOULE À LED

Publication  
**EP 2587114 A4 20141119 (EN)**

Application  
**EP 11800398 A 20110624**

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• JP 2010146713 A 20100628  
• JP 2011003614 W 20110624

Abstract (en)  
[origin: EP2587114A1] In one embodiment, an LED light bulb 1 includes an LED module 2, a base portion on which the LED module 2 is disposed, and a glove 4 attached to the base portion 3. The LED module 2 includes an ultraviolet to violet light-emitting LED chip 8 mounted on a substrate 7. A lighting circuit and a bayonet cap 6 are provided in and on the base portion 3. A fluorescent film 9 is provided on an inner surface of the glove 4, and emits white light by absorbing ultraviolet to violet light emitted from the LED chip 8. The fluorescent film 9 has a film thickness in a range of 80 to 800 µm. In the LED light bulb 1, an amount of ultraviolet light which leaks from the glove 4 is 0.1 mW/nm/lm or less.

IPC 8 full level  
**F21S 2/00** (2006.01); **F21V 3/04** (2006.01); **H01L 33/50** (2010.01); **F21Y 101/02** (2006.01)

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Citation (search report)  
• [I] US 2009002603 A1 20090101 - OTSUKA REIJI [JP], et al  
• [I] DATABASE WPI Week 201040, Derwent World Patents Index; AN 2010-G70279, XP002731137  
• See references of WO 2012001927A1

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AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

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